



Docket No.: M4065.0127A/P137A

#10 Arnold
Accepted
7/8/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Dr. Leonard Forbes, et al.

Application No.: 09/660,324

Group Art Unit: 2823

Filed: September 12, 2000

Examiner: F. Toledo

For: SILICON MULTI-CHIP MODULE
PACKAGING WITH INTEGRATED
PASSIVE COMPONENTS AND
METHOD OF MAKING

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JUL - 8 2002
TECHNOLOGY CENTER 2800

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the telephone interview between Examiner Fernando Toledo and Attorney Chris Tanner on June 12, 2002 and concurrently with the Request for Continued Examination (RCE) filed herewith, please amend the above-identified U.S. Patent application as follows:

In the claims:

122. (Cancel without Disclaimer or Prejudice)

Please add the following new claims.

124. (Newly Added) The process according to claim 90, wherein said step of solder bonding further comprises:

D1